



Summary

I have over 25 years of leading edge technical experience both as a leader and an individual contributor with a record of highly effective, flawless and prolific execution. I can quickly deploy the highly potent mix of EDA tools, programming and circuits expertise. My strengths include excellent communication and analytical skills, breadth of knowledge and ingenuity.

Experience

[2020-Present] Samsung Austin Research Center, Physical Design Consultant

- RTL->GDSII Physical implementation of 3 large GPU blocks to tapeout on a 4nm technology using Cadence Innovus, including floorplanning in SNPS, meeting all area/power/timing requirements. Over 50 timing/DRC/other ECOs. Provide guidance to the CAD team on methodology.
- PnR flow development in SNPS fusion compiler for 3nm (Samsung 3GAP) technology
- Vendor coordination, Wiki documentation

[18-20] Esperanto Technologies, Methodology and Global Clocking Engineer

- Defined physical design methodology for 7nm TSMC process corners and timing margins. Place and route on a million gate low voltage design.
- Design of global clock distribution network for a very large 7nm SoC, model the reconvergent network, simulate with spice, implement using ICC2 and resimulate with extracted spice netlist. Publish chip level clock specification document.
- Setup custom compiler schematic and netlisting environment with extracted views. Characterize PVT sensitivity of library cells and level shifters with spice simulations and publish results.
- Set up and define methodology for an EM/IR flow using Ansys Redhawk/Seascope
- Support and manage PLL, DLL, DDR, PCIE vendors through weekly meetings.
- Publish and maintain Wiki pages for new engineers to help them quickly become productive.

[15-17] Consultant

- Physical design methodology and netlist-to-gds flow development in tcl using Cadence toolset. Also Assura physical verification and logical equivalence (lec) flows.
- Hierarchical implementation of an instance array design including floorplanning, power grid, pin placement, place and route, logical equivalence and physical verification. [Silicon success.](#)
- Abstract generation of analog macros and hierarchical instances to allow for through the block routing.
- Mixed-signal custom CAD support including SKILL programming
- Set up Virtuoso QRC extraction flow for full chip STA, set up and run full chip STA with Tempus, set up and run full chip LEC with Conformal. [Silicon success.](#)

[13-14] Qualcomm Technologies, Senior Staff Engineer

- Top level floorplan, power grid with multiple power domains, using CPF/UPF for a mixed signal design, automated floorplan generation with Tcl. Wrote power intent CPF from scratch. Full chip formal (LEC) and low power (CLP) verification using Cadence tools. Apache Redhawk EM/IR analysis, debug and fixes. My leadership enabled a rare ahead of schedule tapeout. [Silicon success.](#)

[08-13] Consultant

- Developed a 40 nm automated and optimized, tapeout ready, Cadence based implementation flow.
- Wrote Tcl scripts for a correct by construction, tunable flow used for all blocks.
- Developed automated, tapeout ready, STA setup using Primetime-SI using Tcl/Perl scripts.

- Implemented several large blocks at tapeout quality using the above flow ; the resulting GDSII were timing, LEC, LVS/DRC clean. [Silicon success.](#)
- Setup 40nm Cadence based, automated, tapeout ready, block level implementation flow.
- Hierarchical physical implementation flow in 65nm technology using Cadence.
- Telecom ASIC: Implementation of two large blocks using Magma. [Silicon Success.](#)
- 65nm WiFi ASIC: Implementation of large block using Magma. [Silicon Success.](#)
- 65nm WiFi ASIC: Full chip EM/IR signoff using Apache-Redhawk. [Silicon Success.](#)

[06-08] Teranetics, Principal Engineer

- 130nm/65nm 10GBASE-T PHY ASIC: Implement many large blocks, some using [x-route](#). Automate implementation, static timing analysis, logical equivalence and physical verification flows. Power estimation; power reduction using special cells. [Silicon Success.](#)

[04-06] Airgo Networks, Physical Design Manager

- Multiple WiFi ASICs: Implement many blocks using Magma. Automate PTSI STA, formal, Calibre PV flows. Full chip EM/IR signoff using Apache-Redhawk. Tapeout signoff/jobview. ECOs, I/O Spice sims, IP integration, Methodology, project management. [Silicon success.](#)

[01-04] Transmeta, senior Member, Technical Staff

- 1.2/1.8GHz Efficeon CPUs: Implement Hypertransport PnR blocks; Register File design. ECOs. Setup latch compatible STA flow. Array and noise methodologies. Silicon Success ([#1](#),[#2](#)).

[99-01] Sun Microsystems, Member, Technical Staff

- UltraSparc V CPU: CAM Register File, Custom logic circuit design
- 1.2GHz UltraSparc III CPU: Port a dozen 130nm dynamic circuit blocks, including adders up to 64-bits, from 180nm to 130nm. [Silicon success.](#)

[97-99] Intel Corporation, Design Engineer

- 833MHz Pentium III Xeon CPU: High speed dynamic circuit design for L2\$ ECC, L2\$ STA/EM/IR verification. [Silicon success.](#)
- 600 MHz Pentium III CPU : GTL I/O circuit design. [Silicon success.](#)

[94-97] ST Microelectronics, Design Engineer

- Circuit Design of 32kx8, 128kx8 SRAMs. [Silicon success.](#) CAD setup.
- Reverse engineer a register file and re-implement, verify functionality using verilog switch level simulation. [Silicon success.](#)

Education

[\[1989-93\] M.Engg., Electrical Comm, Indian Institute of Science](#)

First class with distinction. [Alumni medal](#), Best Student, 1990-93

[\[1986-89\] B.Sc., Physics, Delhi University.](#)

First class with distinction, Gold medal, [Best Student](#). 1987/88/89.